

Title (en)

Immersed pour tube, installation comprising it, process of manufacture and use thereof.

Title (de)

Gießrohr, Anlage mit einem solchen, Verfahren zur Herstellung und Verwendung des Gießrohres

Title (fr)

Busette de coulée immergée, installation comprenant cette busette, procédé de fabrication et utilisation de cette busette

Publication

**EP 1716945 A1 20061102 (EN)**

Application

**EP 05447092 A 20050426**

Priority

EP 05447092 A 20050426

Abstract (en)

This invention relates to an immersed pour tube (1) for molten metal comprising a body (2) of refractory material, the body (2) having a flow passage (3) for the molten metal, to an installation comprising such a pour tube, to a process for the manufacture of such a pour tube and to the use of such a pour tube in a process for preventing an incident due to the erosion of the pour tube during pouring of a molten metal. According to the invention, the immersed pour tube is characterized by a chamber (4) comprised in the body (2) and connected to a duct (5), the chamber (4) being located in a region of the body which, in use, is under or at the level of the molten metal pool or the slag layer floating on the molten metal. This immersed pour tube can be used to pour molten metal until as close as possible to the break point, without however, reaching the break point of the immersed pour tube and would allow to monitor the erosion of the tube and to take appropriate measures as soon as a break condition is detected.

IPC 8 full level

**B22D 41/50** (2006.01)

CPC (source: EP)

**B22D 41/505** (2013.01)

Citation (search report)

- [X] EP 0589762 A1 19940330 - LORRAINE LAMINAGE [FR]
- [X] PATENT ABSTRACTS OF JAPAN vol. 1999, no. 13 30 November 1999 (1999-11-30)
- [X] PATENT ABSTRACTS OF JAPAN vol. 2000, no. 01 31 January 2000 (2000-01-31)

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